

70V N-Channel Trench MOSFET

General Description

- Trench Power technology
- Low R_{DS(ON)}
- Low Gate Charge
- Optimized for fast-switching applications

Product Summary

 V_{DS} 68V I_{D} (at V_{GS} =10V) 70A

 $R_{DS(ON)}$ (at $V_{GS} = 10V$) < 10.8m Ω

Applications

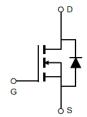
- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

100% UIS Tested



TO-220





Part Number	Package Type	Form	Marking
TTP70N07A	TO-220	Tube	70N07A

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	40	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current B	T _C =25°C		70	Λ
Continuous Drain Current B	T _C =100°C	I _D	49	Α
Pulsed Drain Current ^A		I _{DM}	280	Α
Avalanche Current A		I _{AS}	23	Α
Single Pulse Avalanche Energy L =0.3mH A		E _{AS}	79	mJ
Power Dissipation ^C	T _C =25°C	Б	120	W
	T _C =100°C	P _D	60	W
Junction and Storage Temperature Range		T _J , T _{STG}	-55 to 175	°C

Thermal Characteristics

Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Case	Steady-State	R _{eJC}	1.24	00.004	
Maximum Junction-to-Ambient	Steady-State	R _{eJA}	62.5	°C/W	



Cumbal	Baramatar			Value			1124
Symbol	Parameter Conditions			Min	Тур	Max	Units
STATIC P	ARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$		40			V
	7 0 / 1/1 0 / 1	$V_{DS} = 40V, V_{GS} = 0V$	T _J =25°C			1	μА
I _{DSS}	Zero Gate Voltage Drain Current		T _J =100°C			25	
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	•			±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		2	3	4	V
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =10V, I _D =30A			8.5	10.8	mΩ
g _{FS}	Forward Transconductance	$V_{DS} = 10V, I_{D} = 30A$			17.1		S
V _{SD}	Diode Forward Voltage	I _S =30A, V _{GS} =0V				1	V
I _s	Maximum Body-Diode Continuous Current ^B				70	Α	
DYNAMIC	PARAMETERS						
C _{iss}	Input Capacitance	$V_{GS} = 0V, V_{DS} = 20V, f = 1MH_Z$			4570		
C _{oss}	Output Capacitance				1410		pF
C _{rss}	Reverse Transfer Capacitance				734		
SWITCHIN	NG PARAMETERS						
Q _g (10V)	Total Gate Charge	V _{GS} =10V,V _{DS} =20V, I _D =40A			70		
Q_{gs}	Gate Source Charge				20		nC
Q_{gd}	Gate Drain Charge				17		
t _{D(on)}	Turn-On Delay Time	$V_{GS} = 10V, V_{DS} = 20V, I_{D} = 40A,$ $R_{G} = 2.5\Omega$			8		
t _r	Turn-On Rise Time				7		20
$T_{D(off)}$	Turn-Off Delay Time				40		ns
t _f	Turn-Off Fall Time				15		
t _{rr}	Body Diode Reverse Recovery Time	1 -20A di/dt -400A/:	10		30		ns
Q _{rr}	Body Diode Reverse Recovery Charge	I _F =20A, di/dt =100A/μs			45		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)} = 175$ °C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

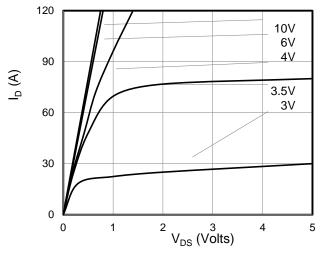


Figure 1: On-Region Characteristics

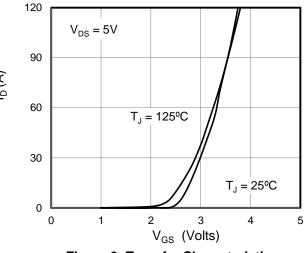


Figure 2: Transfer Characteristics

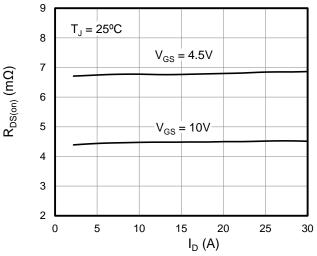


Figure 3: On-Resistance vs. Drain Current

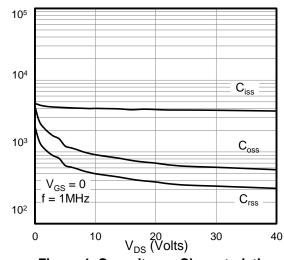


Figure 4: Capacitance Characteristics

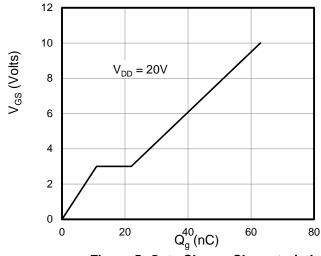


Figure 5: Gate Charge Characteristics

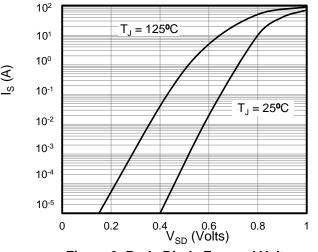


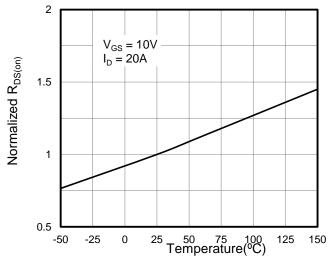
Figure 6: Body Diode Forward Voltage

Capacitance (pF)

 $Z_{\theta\,\text{JC}}$ Normalized Transient Thermal Resistance

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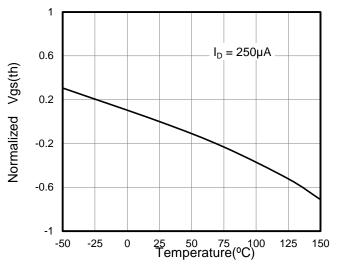
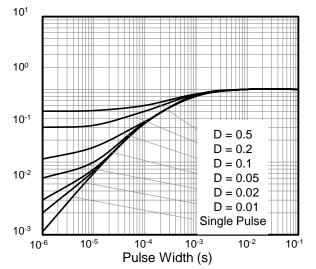


Figure 7: On-Resistance vs. Junction Temperature

Figure 8: Vgs(th) vs. Junction Temperature



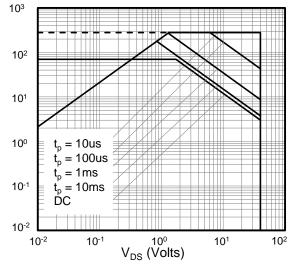


Figure 11: Normalized Transient Thermal Resistance

Figure 12: Safe Operating Area

I_D (Amps)

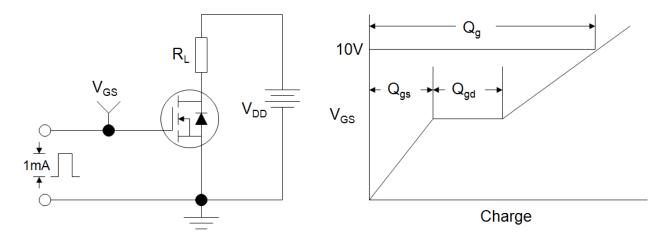


Figure A: Gate Charge Test Circuit and Waveforms

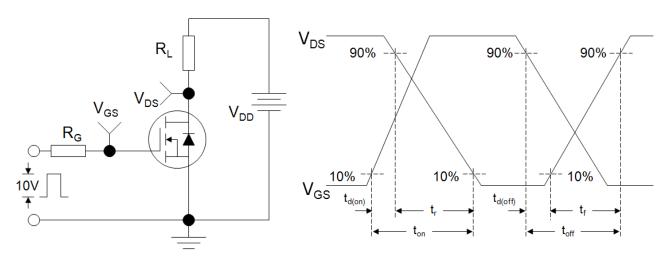


Figure B: Resistive Switching Test Circuit and Waveforms

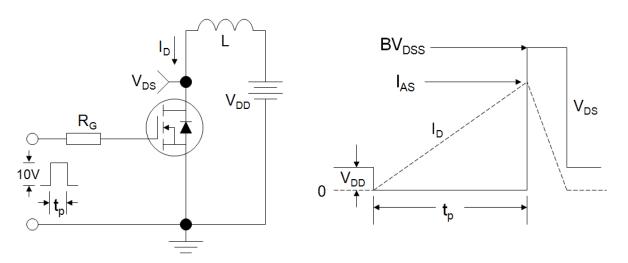
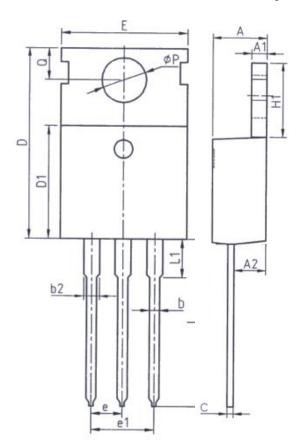
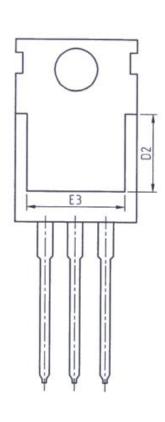


Figure C: Unclamped Inductive Switching (UIS) Test Circuit and Waveforms



TO-220(华天)





Unit: mm			
Symbol	Min.	Max.	
Α	4. 37	4. 77	
A1	1. 25	1. 45	
A2	2. 20	2. 60	
b	0. 70	0. 95	
b2	1. 17	1. 47	
С	0. 40	0. 65	
D	15. 10	16. 10	
D1	8. 80	9. 40	
D2	5. 50	_	

Unit: mm			
Symbol	Min.	Max.	
E	9. 70	10. 30	
E3	7. 00	-	
е	2. 54BSC		
e1	5. 08BSC		
H1	6. 25	6. 85	
L	12. 75	13.80	
L1	_	3. 40	
Р	3. 40	3. 80	
Q	2. 60	3. 00	



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